

Serial No. 09/863,948
May 13, 2004
Reply to Office Action of December 16, 2003
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AMENDMENTS TO THE SPECIFICATION:

Please replace the last full paragraph on page 8, with the following new paragraph:

The solder balls 30 are preferably reflowed onto the ends of the pins 26 extending from the first major surface 36 of a respective connector portion 20. This is accomplished by heating the solder balls 30 sufficiently to soften the solder balls 30 and then extending the pins 26 thereinto. The so-impaled solder balls 30 are then cooled and resolidified. The pins 26 may be extended substantially into the solder balls 30 (see FIG. 5, configuration A) or just far enough in to secure the resolidified solder balls 30 onto the pins (see FIG. 5, configurations B and C). As seen in Fig. 5, the solder balls 30 each have a diameter that is larger than a diameter of an end portion of the pins 26 that extend into the solder balls 30.